



SOT1372-1

plastic thermal enhanced very thin small package; no leads;
8 terminals; body 3 x 2 x 0.35 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOT1372
Package type industry code	X2SON8
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-5-2014

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.9	-	2	2.1	mm
E	package width		2.9	-	3	3.1	mm
A	seated height		0.32	-	0.33	0.35	mm
e	nominal pitch		-	-	0.5	-	mm
n ₂	actual quantity of termination		-	-	8	-	



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2. Package outline

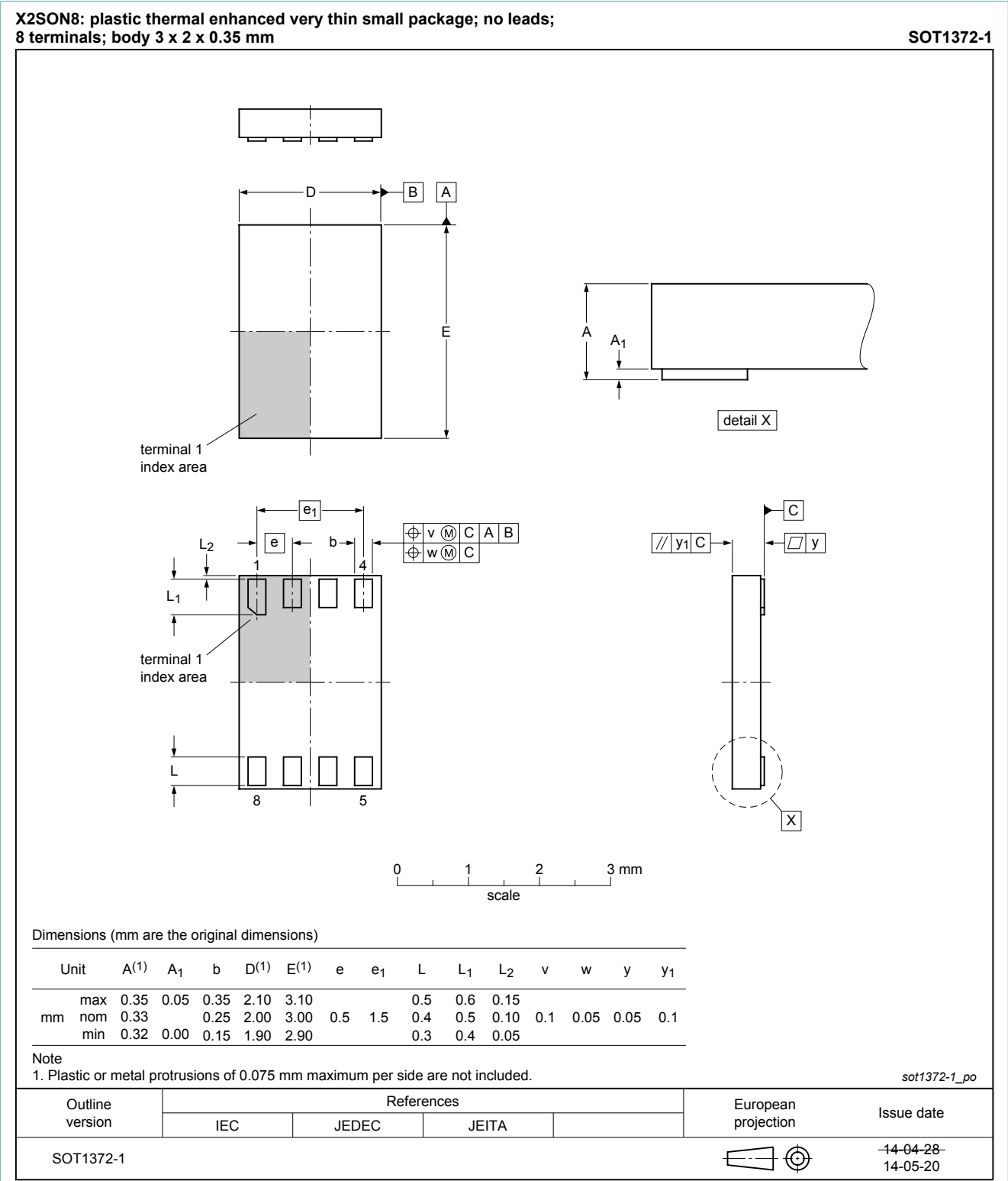


Fig. 1. Package outline X2SON8 (SOT1372-1)

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3. Legal information

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